## 87C196CA/87C196CB 16 MHz ADVANCED 16-BIT CHMOS MICROCONTROLLER WITH INTEGRATED CAN 2.0

### Express

### **Product Features**

### -40°C to +85°C Ambient

- High Performance CHMOS 16-Bit CPU
- Up to 32 Kbytes of On-Chip EPROM
- Up to 1 Kbyte of On-Chip Register RAM
- Up to 512 Bytes of Additional RAM (Code RAM)
- Register-Register Architecture
- 8 Channel/10-Bit A/D with Sample/Hold
- **37** Prioritized Interrupts
- Up to Seven 8-Bit (56) I/O Ports
- Full Duplex Serial I/O Port
- Dedicated Baud Rate Generator
- Interprocessor Communication Slave Port
- Selectable Bus Timing Modes for Flexible Interfacing
- Oscillator Fail Detection Circuitry

High Speed Peripheral Transaction Server

Advance Information Datasheet

- (PTS)Two Dedicated 16-Bit High-Speed Compare Registers
- 10 High Speed Capture/Compare (EPA)
- Full Duplex Synchronous Serial I/O Port (SSIO)
- Two Flexible 16-Bit Timer Counters
- Quadrature Counting Inputs
- Flexible 8-/16-Bit External Bus (Programmable)
- Programmable Bus (HLD/HLDA)
- 1.4 μs 16 x 16 Multiply
- 2.4 μs 32/16 Divide
- 68-Pin PLCC Package for 87C196CA
- 84-Pin PLCC Package for 87C196CB
- 16 MHz Operation

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### 1.0 INTRODUCTION

The 87C196CA/87C196CB - *Express* are members of the MCS<sup>®</sup> 96 microcontroller family. These devices are based upon the MCS 96 Kx/Jx microcontroller product families with enhancements ideal for automotive and industrial applications. The CA/CB are the first devices in the Kx family to support networking through the integration of the CAN 2.0 (Controller Area Network) peripheral on-chip. The 87C196CB offers the highest memory density of the MCS 96 microcontroller family, with 56K of on-chip EPROM, 1.5K of on-chip register RAM, and 512 bytes of additional RAM (Code RAM). In addition, the 87C196CB provides up to 16 Mbyte of Linear Address Space. The 87C196CA is a sub-set of the CB, offering 32K of on-chip EPROM, up to 1.0 K of on-chip register.

### **Table 1. Device Overview**

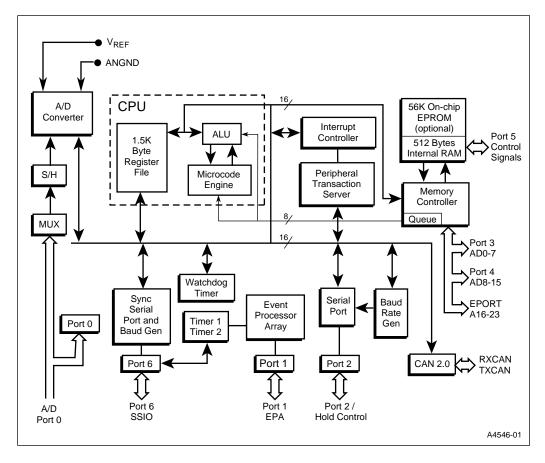
Device	Pins/Pac kage	EPROM	Reg RAM	Code RAM	I/O	EPA	SIO	SSIO	CAN	A/D	Addr Space
87C196CB	84-Pin PLCC	56K	1.5K	512b	56	10	Y	Y	Y	8	1 Mbyte
87C196CA	68-Pin PLCC	32K	1.0K	256b	38	6	Y	Y	Y	6	64 Kbyte

### 2.0 BLOCK DIAGRAM

The MCS 96 microcontroller family members are all high-performance microcontrollers with a 16-bit CPU. The 87C196CB is composed of the high-speed (16 MHz) macrocore with up to 16 Mbyte linear address space, 56 Kbytes of program EPROM, up to 1.5 Kbytes of register RAM, and up to 512 bytes of code RAM (16-bit addressing modes) with the ability to execute from this RAM space. It supports the high-speed, serial communications protocol CAN 2.0, with 15 message objects of 8 bytes data length, an 8-channel, 10-bit / 3 LSB analog to digital converter with programmable S/H times, and conversion times k 20 ms at 16 MHz. It has an asynchronous serial I/O port (SIO) with a dedicated 16-bit baud rate generator, an additional synchronous serial I/O port (SSIO) with full duplex master/slave transceivers, a flexible timer/counter structure with prescaler, cascading, and quadrature capabilities. There are ten modularized, multiplexed, high-speed I/O for capture and compare (called Event Processor Array) with 200 ns resolution and double buffered inputs, and a sophisticated prioritized interrupt structure with programmable Peripheral Transaction Server (PTS) implementing several channel modes, including single/burst block transfers from any memory location to any memory location, a PWM and PWM toggle mode to be used in conjunction with the EPA, and an A/D scan mode.

*Note:* This is an advance information data sheet. The AC and DC parameters contained within this data sheet may change after full express temperature characterization of the device has been performed. Contact your local sales office before finalizing the timing and DC characteristics of a design to verify you have the latest information.

### Figure 1. 8XC196CB Block Diagram



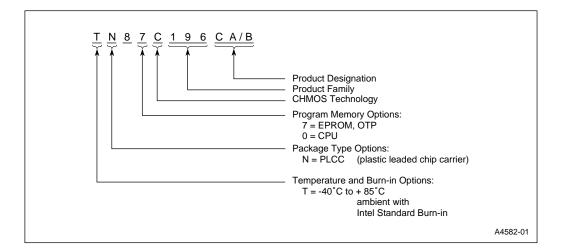
## 3.0 PROCESS INFORMATION

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These devices are manufactured on P629.5, a CHMOS III-E process. Additional process and reliability information is available in Intel's *Components Quality and Reliability Handbook*, Order Number 210997.

All thermal impedance data is approximate for static air conditions at 1 W of power dissipation. Values change depending on operation conditions and applications. See the Intel *Packaging Handbook* (order number 240800) for a description of Intel's thermal impedance test methodology.

### Figure 2. The 87C196CA/87C196CB - Express Family Nomenclature



### **Table 1. Thermal Characteristics**

Device and Package	$\Theta_{JA}$	ΘJC
TN87C196CB (84-Lead PLCC Package)	35°C/W	11°C/W
TN87C196CA (68-Lead PLCC Package)	36.5°C/W	10°C/W

NOTES:

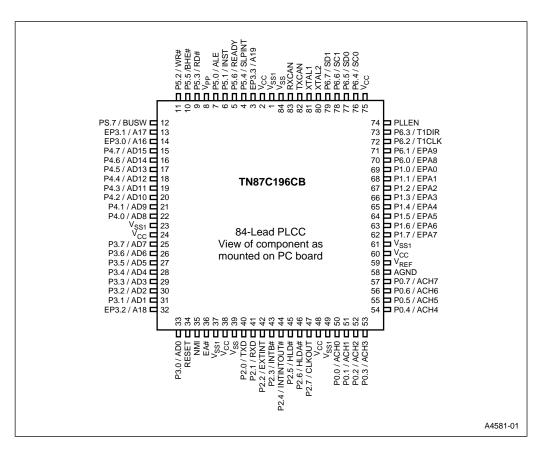
 Θ<sub>JA</sub> = Thermal resistance between junction and the surrounding environment (ambient) measurements are taken 1 ft. away from case in air flow environment.

 $\Theta_{JV}$  = Thermal resistance between junction and package face (case).

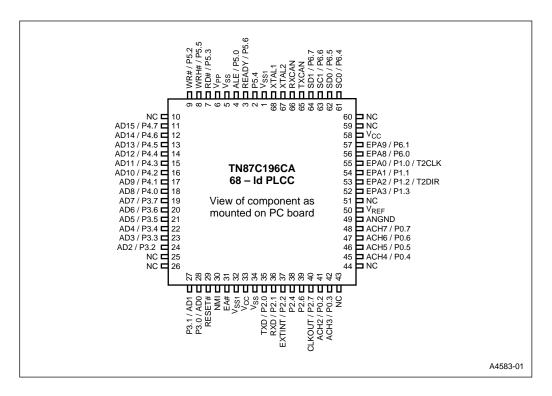
 All values of Θ<sub>JA</sub> and Θ<sub>JC</sub> may fluctuate depending on the environment (with or without airflow, and how much airflow) and device power dissipation at temperature of operation. Typical variations are ± 2°C/W.

3. Values listed are at a maximum power dissipation of 1 W.

### Figure 3. 84-Pin PLCC TN87C196CB Diagram



### Figure 4. 68-Pin PLCC TN87C196CA Diagram



## 4.0 PIN DESCRIPTIONS

### Table 2. Pin Descriptions (Sheet 1 of 3)

Name	Description
V <sub>CC</sub>	Main supply voltage (+5 V).
V <sub>SS</sub> , V <sub>SS1</sub>	Digital circuit ground (0 V). There are seven $V_{SS}$ pins CB (4 on CA), all of which MUST be connected to a single ground plane.
V <sub>REF</sub>	Reference for the A/D converter (+5 V). $V_{\rm REF}$ is also the supply voltage to the analog portion of the A/D converter and the logic used to read Port 0. Must be connected for A/D and Port 0 to function.
V <sub>PP</sub>	Programming voltage for the EPROM parts. It should be +12.5 V for programming. It is also the timing pin for the return from powerdown circuit. Connect this pin with a 1 $\mu$ F capacitor to V <sub>SS</sub> and a 1 M $\Omega$ resistor to V <sub>CC</sub> . If this function is not used, V <sub>PP</sub> may be tied to V <sub>CC</sub> .
ANGND	Reference ground for the A/D converter. Must be held at nominally the same potential as $V_{\mbox{SS}}.$
XTAL1	Input of the oscillator inverter and the internal clock generator.
XTAL2	Output of the oscillator inverter.
RESET#	Reset input to the chip. Input low for at least 16 state times resets the chip. The subsequent low-to-high transition resynchronizes CLKOUT and commences a 10-state time sequence in which the PSW is cleared, bytes are read from 2018H, 201AH and 201CH (if enabled) loading the CCBs, and a jump to location 2080H is executed. Input high for normal operation. RESET# has an internal pullup.
NMI	A positive transition causes a non-maskable interrupt vector through memory location 203EH. If not used, this pin should be tied to $V_{SS}$ . May be used by Intel Evaluation boards.
EA#	Input for memory select (External Access). EA# equal to a high causes memory accesses to locations 0FF2000H through 0FFFFFH to be directed to on-chip EPROM/ROM. EA# equal to a low causes accesses to these locations to be directed to off- chip memory. EA# = +12.5 V causes execution to begin in the Programming Mode. EA# latched at reset.
PLLEN (196CB only)	Selects between PLL mode or PLL bypass mode. This pin must be either tied high or low. PLLEN pin = 0, bypass PLL mode. PLLEN pin = 1, places a 4x PLL at the input of the crystal oscillator. Allows for a low frequency crystal to drive the device (i.e., 5 MHz = 16 MHz operation).
P6.4-6.7/SSIO	Dual-function I/O ports that have a system function as Synchronous Serial I/O. Two pins are clocks and two pins are data, providing full duplex capability. Also, LSIO when not used as SSIO.
P6.3/T1DIR (CB only)	Dual-function I/O pin. Primary function is that of a bidirectional I/O pin, however, it may also be used as a TIMER1 Direction input. The TIMER1 increments when this pin is high and decrements when this pin is low.
P6.2/T1CLK (CB only)	Dual-function I/O pin. Primary function is that of a bidirectional I/O pin, however may also be used as a TIMER1 Clock input. The TIMER1 increments or decrements on both positive and negative edges of this pin.
P6.0-6.1/EPA8-9	Dual-function I/O port pins. Primary function is that of bidirectional I/O. System function is that of High Speed capture and compare.
P5.7/BUSWIDTH (CB only)	Input for bus width selection. If CCR bit 1 is a one and CCR1 bit 2 is a one, this pin dynamically controls the Buswidth of the bus cycle in progress. If BUSWIDTH is low, an 8-bit cycle occurs, if BUSWIDTH is high, a 16-bit cycle occurs. If CCR bit 1 is "0" and CCR1 bit 2 is "1", all bus cycles are 8-bit, if CCR bit 1 is "1" and CCR1 bit 2 is "0", all bus cycles are 16-bit. CCR bit 1 = "0" and CCR1 bit 2 = "0" is illegal. Also an LSIO pin when not used as BUSWIDTH.

### Table 2. Pin Descriptions (Sheet 2 of 3)

Name	Description
P5.6/READY	Ready input to lengthen external memory cycles, for interfacing with slow or dynamic memory, or for bus sharing. If the pin is high, CPU operation continues in a normal manner. If the pin is low prior to the falling edge of CLKOUT, the memory controller goes into a wait state mode until the next positive transition in CLKOUT occurs with READY high. When external memory is not used, READY has no effect. The max number of wait states inserted into the bus cycle is controlled by the CCR/CCR1. Also an LSIO if READY is not selected.
P5.5/BHE#/WRH#	Byte High Enable or Write High output, as selected by the CCR. BHE# = 0 selects the bank of memory that is connected to the high byte of the data bus. $A0 = 0$ selects the bank of memory that is connected to the low byte. Thus accesses to a 16-bit wide memory can be to the low byte only ( $A0 = 0$ , BHE# = 1), to the high byte only ( $A0 = 1$ , BHE# = 0) or both bytes ( $A0 = 0$ , BHE# = 0). If the WRH# function is selected, the pin goes low if the bus cycle is writing to an odd memory location. BHE#/WRH# is only valid during 16-bit external. Also an LSIO pin when not BHE/WRH#.
P5.4/SLPINT	Dual-function I/O pin. As a bidirectional port pin or as a system function. The system function is a Slave Port Interrupt Output Pin (on CA, bidirectional port pin only).
P5.3/RD#	Read signal output to external memory. RD# is active only during external memory reads or LSIO when not used as RD#.
P5.2/WR#/WRL#	Write and Write Low output to external memory, as selected by the CCR, WR# goes low for every external write, while WRL# goes low only for external writes where an even byte is being written. WR#/WRL# is active during external memory writes. Also an LSIO pin when not used as WR#/WRL#.
P5.1/INST (CB only)	Output high during an external memory read indicates the read is an instruction fetch. INST is valid throughout the bus cycle. INST is active only during external memory fetches, during internal EPROM fetches INST is held low. Also LSIO when not INST.
P5.0/ALE/ADV#	Address Latch Enable or Address Valid output, as selected by CCR. Both pin options provide a latch to demultiplex the address from the address/data bus. When the pin is ADV#, it goes inactive (high) at the end of the bus cycle. ADV# can be used as a chip select for external memory. ALE/ADV# is active only during external memory accesses. Also LSIO when not used as ALE.
PORT3 and 4	8-bit bidirectional I/O ports with open drain outputs. These pins are shared with the multiplexed address/data bus which has strong internal pullups.
P2.7/CLKOUT	Output of the internal clock generator. The frequency is the oscillator frequency. CLKOUT has a 50% duty cycle. Also LSIO pin when not used as CLKOUT.
P2.6/HLDA#	Bus Hold Acknowledge. Active-low output indicates that the bus controller has relinquished control of the bus. Occurs in response to an external device asserting the HLD# signal. Also LSIO when not used as HLDA#.
P2.5/HLDÝ (CB only)	Bus Hold. Active-low signal indicates that an external device is requesting control of the bus. Also LSIO when not used as HLD#.
P2.4/INTOUT#	Interrupt Output. This active-low output indicates that a pending interrupt requires use of the external bus. Also LSIO when not used as INTOUT#.
P2.3/BREQ# (CB only)	Bus Request. This active-low output signal is asserted during a HOLD cycle when the bus controller has a pending external memory cycle. Also LSIO when not used as BREQ#.
P2.2/EXTINT	A positive transition on this pin causes a maskable interrupt vector through memory location 203CH. Also LSIO when not used as EXTINT.
P2.1/RXD	Receive data input pin for the Serial I/O port. Also LSIO if not used as RXD.
P2.0/TXD	Transmit data output pin for the Serial I/O port. Also LSIO if not used as TXD.
PORT 1/EPA0-7	Dual-function I/O port pins. Primary function is that of bidirectional I/O. System function is that of High Speed capture and compare. EPA0 and EPA2 have another function of T2CLK and T2DIR of the TIMER2 timer/counter.

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### Table 2. Pin Descriptions (Sheet 3 of 3)

Name	Description
PORT 0/ACH0-7	8-bit high impedance input-only port. These pins can be used as digital inputs and/or as analog inputs to the on-chip A/D converter. These pins are also used as inputs to EPROM parts to select the Programming Mode.
EPORT (CB only)	8-bit bidirectional standard and I/O Port. These bits are shared with the extended address bus, A16–A19 for CB PLCC. Pin function is selected on a per pin basis.
TXCAN	Push-pull output to the CAN bus line.
RXCAN	High impedance input-only from the CAN bus line.

### Table 3. 87C196CB Memory Map

Address	Description	Notes
FFFFFH FF2080H	Program Memory - Internal EPROM or External Memory (Determined by EA# Pin)	
FF207FH FF2000H	Special Purpose Memory - Internal EPROM or External Memory (Determined by EA# Pin)	
FF1FFFH FF0600H	External Memory	
FF05FFH FF0400H	Internal RAM (Identically Mapped into 00400H±005FFH)	
FF03FFH FF0100H	External Memory	
FF00FFH FF0000H	Reserved for ICE	
FEFFFFH 0F0000H	Overlaid Memory (External)	(5)
0EFFFFH 010000H	900 Kbytes External Memory	
00FFFFH 002080H	External Memory or Remapped OTPROM (Program Memory)	(1)
00207FH 002000H	External Memory or Remapped OTPROM (Special Purpose Memory)	(1,3)
001FFFH 001FE0H	Memory Mapped Special Function Registers (SFR's)	
001FDFH 001F00H	Internal Peripheral Special Function Registers (SFR's)	(5)
001EFFH 001E00H	Internal CAN Peripheral Memory	(5)
001DFFH 001C00H	Internal Register RAM	
001BFFH 000600H	External Memory	

NOTES:

1. These areas are mapped internal EPROM if the REMAP bit (CCB2.2) is set and EA# = 5 V. Otherwise they are external memory. 2. Code executed in locations 0000H to 003FFH is forced external.

3. Reserved memory locations must contain 0FFH unless noted.

Reserved SFR bit locations must be written with 0.
 Refer to *8XC196CB User's Guide* for SFR, CAN and Paging Descriptions.

### Table 3. 87C196CB Memory Map

Address	Description	Notes
0005FFH 000400H	Internal RAM (Code RAM) (Address with Indirect or Indexed Modes)	
0003FFH 000100H	Register RAM $\pm$ Upper Register File (Address with Indirect or Indexed Modes or through Windows.)	(2)
0000FFH 000018H	Register RAM $\pm$ Lower Register File. (Address with Direct, Indirect, or Indexed Modes.)	(2)
000017H 000000H	CPU SFR's	(4)

NOTES:

1. These areas are mapped internal EPROM if the REMAP bit (CCB2.2) is set and EA# = 5 V. Otherwise they are external memory. 2. Code executed in locations 0000H to 003FFH is forced external.

3. Reserved memory locations must contain 0FFH unless noted.

4. Reserved SFR bit locations must be written with 0.

5. Refer to 8XC196CB User's Guide for SFR, CAN and Paging Descriptions.

### Table 4. 87C196CA Memory Map

Address	Description	Notes
00FFFFH 00A000H	External Memory	
009FFFH 002080H	Internal EPROM (32 Kbytes)	
00207FH 002000H	(Determined by EA# Pin) Reserved Memory (Internal EPROM or External Memory)	
001FFFH 001FE0H	Memory Mapped Special Function Registers (SFR's)	
001FDFH 001F00H	Internal Special Function Registers (SFR's)	(1)
001EFFH 001E00H	Internal CAN Peripheral Memory	
001DFFH 000500H	External Memory	
0004FFH 000400H	(Address with Indirect or Indexed Modes) Internal RAM (Code RAM)	
0003FFH 000100H	Internal Register RAM – Upper Register File (Address with Indirect or Indexed Modes or through Windows)	(2)
0000FFH 000018H	Internal Register RAM – Lower Register File (Address with Direct, Indirect, or Indexed Modes.	(2)
000017H 000000H	CPU Special Function Registers (SFR's)	(2,3)

NOTES:

Refer to 8XC196KX Family User's Guide for SFR Description.
 Code executed in locations 0000H to 003FFH is forced external.

3. Reserved SFR bit locations must be written with 0.

ССВ (20	18H: Byte)	)		сс	<b>B1</b> (201	AH: Byte	e)			
0 PD	= "1	I" Enables Pov	0	CCR	2 =	"1	" Feto	ch CCB2 ("0" for CA		
1 BW0	) = S	ee Table	1	IRC2	2 =	S	ee Ta	ble		
2 WR	= "1	I" = WR#/BHE	- "0" = WRL#/WRH#	2	BW1	=	= See Table			
3 ALE	= "1	I" = ALE - "0" =	ADV	3	WDE	=	"0	"0" = Always Enabled		
4 IRC0				4	1	_	R	eserv	ed Must Be "1"	
5 IRC1	<b>│</b> <sub>=</sub>	See Table		5	0	=	R	eserv	ed Must Be "1"	
6 LOC				6	MEMSE	=	S	See Table		
7 LOC	1 <sub>=</sub> }	See Table		7	MEMSE	EL1 =	S	ee Ta	ble	
	C	CCB2 (201CH:	Byte) (CB Only)							
	C	0	= Reserved Mu	st B	e "0"					
	1	MODE16	= Select 16-Bit	or 2	4-Bit Mo	de				
	2	2 REMAP							ent 0FFH only ment 00H	
	3	3 1	= Reserved Mu		-		ianc	Jey		
	4	1	= Reserved Mu	st B	e "1"					
	5	5 1	= Reserved Mu	st B	e "1"					
	6	6 1	= Reserved Mu	st B	e "1"					
	7	7 1	= Reserved Mu	st B	e "1"					
LOC1	LOC0	Fur	nction		RC2	IRC1	IR	C0	Max Wait States	
0	0	Read and Wr	ite Protected		0	0		0	Zero Wait States	
0	1	Write Protect			1	0		0	1 Wait State	
1	0	Read Protect	ed Only		1	0	-		2 Wait States	
1	1	No Protection	1		1	1	1 (		3 Wait States	
					1	1		1	INFINITE	
	1					1				
MSEL1	MSEL		s Timing Mode		BW1	BW	-	Bus Width		
0		Mode 0 (	1-Wait KR)		0	0		ILLE		
0 1	1 0	Mode 1 Mode 2			0 1	1 0		16-Bit Only		
1	1	Mode 3 (I	KR)		1	1		8-Bit Only BW Pin Controlled		
Mode 0 (1-Wait I	<r):< td=""><td>0</td><td>imilar to the 87C196k section for actual timi</td><td></td><td></td><td>g with 1 a</td><td>auton</td><td>natic</td><td>wait state.</td></r):<>	0	imilar to the 87C196k section for actual timi			g with 1 a	auton	natic	wait state.	

### Figure 5. Chip Configuration Registers

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#### 5.0 ELECTRICAL CHARACTERISTICS

#### **ABSOLUTE MAXIMUM RATINGS\***

Storage Temperature	–60°C to +150°C
Voltage from V <sub>PP</sub> or EA# to V <sub>SS</sub> or ANGND	–0.5 V to +13.0 V
Voltage from any other pin to V <sub>SS</sub> or ANGND This includes V <sub>PP</sub> on ROM an	–0.5 V to +7.0 V d CPU devices.
Power Dissipation	0.5 W

#### **OPERATING CONDITIONS**

T <sub>A</sub> (Ambient Temperature Under Bias)40°C to +85°C					
V <sub>CC</sub> (Digital Supply Voltage)	4.5 V to 5.5 V				
V <sub>REF</sub> (Analog Supply Voltage)	4.5 V to 5.5 V				
F <sub>OSC</sub> (Oscillator Frequency)	4 MHz to 16 MHz				

NOTE: ANGND and  $V_{SS}$  should be nominally at the same potential.

NOTICE: This is a production data sheet. The specifications are subject to change without notice. Verify with your local Intel sales office that you have the latest datasheet before finalizing a design.

\*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

#### 5.1 DC CHARACTERISTICS

### Table 5. DC Characteristics (Under Listed Operating Conditions) (Sheet 1 of 2)

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
Icc	V <sub>CC</sub> Supply Current (-40°C to +85°C Ambient) CA CB			90 100	mA	$\label{eq:cc} \begin{array}{l} {\sf XTAL1} = 16 \; {\sf MHz} \\ {\sf V}_{\rm CC} = {\sf V}_{\rm PP} = {\sf V}_{\rm REF} = 5.5 \; {\sf V} \\ ({\sf While Device in Reset}) \end{array}$
I <sub>REF</sub>	A/D Reference Supply Current			5	mA	
I <sub>IDLE</sub>	Idle Mode Current CA CB			40 35	mA	XTAL1 = 16 MHz V <sub>CC</sub> = V <sub>PP</sub> = V <sub>REF</sub> = 5.5 V
I <sub>PD</sub>	Powerdown Mode Current		50	TBD	μA	$V_{CC} = V_{PP} = V_{REF} = 5.5 V$ (Notes 6,9)
V <sub>IL</sub>	Input Low Voltage (All Pins)	-0.5		0.3 V <sub>CC</sub>	V	For PORT0 (Note 8)
V <sub>IH</sub>	Input High Voltage	0.7 V <sub>CC</sub>		V <sub>CC</sub> + 0.5	V	For PORT0 (Note 8)

NOTES:

1. All BD (bidirectional) pins except INST and CLKOUT. INST and CLKOUT are excluded due to not being weakly pulled high in reset. BD pins include Port1, Port2, Port3, Port4, Port5 and Port6 except SPLINT (P5.4) and HLDA (P2.6).

2. Standard Input pins include XTAL1, EA#, RESET and Port 1/2/5/6 when setup as inputs.

3. All Bidirectional I/O pins when configured as Outputs (Push/Pull).

4. Device is Static and should operate below 1 Hz, but only tested down to 4 MHz.

5. Maximum  $I_{OL}$  / $I_{OH}$  currents per pin are characterized and published at a later date.

6. Typicals are based on limited number of samples and are not guaranteed. The values listed are at room temperature and  $V_{REF} = V_{CC} = 5 V$ . 7. Violating these specifications in reset may cause the device to enter test mode (P5.4 and P2.6).

8. When P0 is used as analog inputs, refer to A/D specifications for this characteristic.

9. For temperatures < 100°C typical is 10 µA.



Symbol	Parameter	Min	Тур	Мах	Units	Test Conditions
V <sub>OL</sub>	Output Low Voltage (Outputs Configured as Complementary)			0.3 0.45 1.5	V	I <sub>OL</sub> = 200 μA (Note 3,5) I <sub>OL</sub> = 3.2 mA I <sub>OL</sub> = 7 mA
V <sub>OH</sub>	Output High Voltage (Output Configured as Complementary)	$V_{CC} - 0.3$ $V_{CC} - 0.7$ $V_{CC} - 1.5$			V	$I_{OH} = -200 \ \mu A \text{ (Note 3,5)}$ $I_{OH} = -3.2 \ \text{mA}$ $I_{OH} = -7 \ \text{mA}$
ILI	Input Leakage Current (Standard Inputs)			±10	μA	$V_{SS} < V_{IN} < V_{CC}$
I <sub>LI1</sub>	Input Leakage Current (Port 0)			CA ±1.5 CB ±1	μA	$V_{SS} < V_{IN} < V_{REF}$
V <sub>OH1</sub>	SPLINT (P5.4) and HLDA (P2.6) Output High Voltage in RESET			2	V	I <sub>OH</sub> = 0.8 mA (Note 7)
V <sub>OH2</sub>	Output High Voltage in RESET	V <sub>CC</sub> – 1			V	I <sub>OH</sub> = -15 μA (Note 1)
CS	Pin Capacitance (Any Pin to V <sub>SS</sub> )			10	pF	F <sub>TEST</sub> = 1 MHz (Note 6)
R <sub>RST</sub>	Reset Pull-up Resistor (CB)	65 K		180 K	Ω	For CB
R <sub>RST</sub>	Reset Pull-up Resistor (CA)	6 K		65 K	Ω	For CA
R <sub>WPU</sub>	Weak Pull-up Resistance (Approximate)	9	150 K		Ω	(Note 6)

### Table 5. DC Characteristics (Under Listed Operating Conditions) (Sheet 2 of 2)

NOTES:

1. All BD (bidirectional) pins except INST and CLKOUT. INST and CLKOUT are excluded due to not being weakly pulled high in reset. BD pins include Port1, Port2, Port3, Port4, Port5 and Port6 except SPLINT (P5.4) and HLDA (P2.6).

2. Standard Input pins include XTAL1, EA#, RESET and Port 1/2/5/6 when setup as inputs.

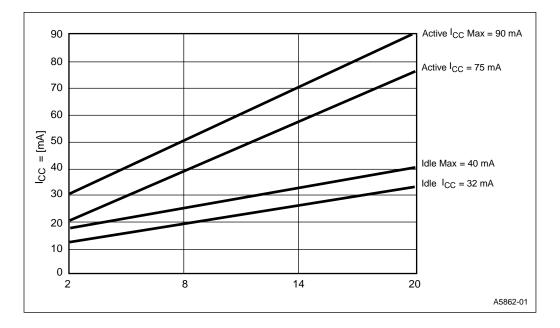
3. All Bidirectional I/O pins when configured as Outputs (Push/Pull).

4. Device is Static and should operate below 1 Hz, but only tested down to 4 MHz.

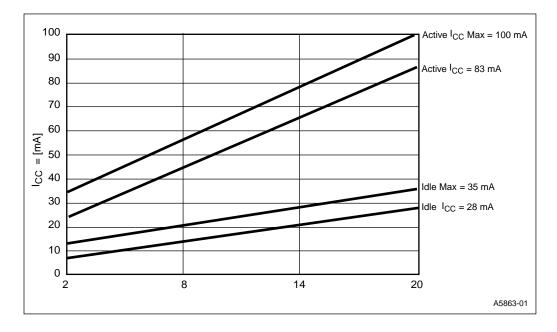
- 5. Maximum I<sub>OL</sub> /I<sub>OH</sub> currents per pin are characterized and published at a later date.
   6. Typicals are based on limited number of samples and are not guaranteed. The values listed are at room temperature and  $V_{REF} = V_{CC} = 5 V$ . 7. Violating these specifications in reset may cause the device to enter test mode (P5.4 and P2.6). 8. When P0 is used as analog inputs, refer to A/D specifications for this characteristic.

9. For temperatures <  $100^{\circ}$ C typical is  $10 \mu$ A.

### Figure 6. 87C196CA I<sub>CC</sub> vs Frequency



### Figure 7. 87C196CB I<sub>CC</sub> vs Frequency





#### 5.1.1 8xC196CB Additional Bus Timing Modes

The 8xC196CB device has two bus timing modes for external memory interfacing.

#### 5.1.1.1 MODE 3

Mode 3 is the standard timing mode. Use this mode for systems that emulate the 8xC196KR bus timings.

#### 5.1.1.2 **MODE 0**

Mode 0 is the standard timing mode, but 1 (minimum) wait state is always inserted in external bus cycles.

#### 5.2 **AC CHARACTERISTICS**

#### 5.2.1 **Test Conditions**

- Capacitive load on all pins = 100 pF
- Rise and Fall Times = 10 ns

### Table 6. AC Characteristics the 87C196CA/87C196CB - Express Meets (Sheet 1 of 2)

Symbol	Parameter	Min	Мах	Units
F <sub>XTAL</sub>	Frequency on XTAL1	4	16	MHz (1)
T <sub>OSC</sub>	XTAL1 Period (1/F <sub>XTAL</sub> )	62.5	250	ns
T <sub>XHCH</sub>	XTAL1 High to CLKOUT High or Low	+ 20	110	ns
T <sub>OFD</sub>	Clock Failure to Reset Pulled Low	4	40	µs (6)
T <sub>CLCL</sub>	CLKOUT Period	27,	OSC	ns
T <sub>CHCL</sub>	CLKOUT High Period	T <sub>OSC</sub> -10	T <sub>OSC</sub> +15	ns
T <sub>CLLH</sub>	CLKOUT Low to ALE/ADV High	-15	+ 10	ns
T <sub>LLCH</sub>	ALE/ADV# Lowe to CLKOUT High	-20	+ 15	ns
T <sub>LHLH</sub>	ALE/ADV# Cycle Time	4T,	osc	ns (5)
T <sub>LHLL</sub>	ALE/ADV# High Time	T <sub>OSC</sub> -10	T <sub>OSC</sub> +10	ns
T <sub>AVLL</sub>	Address Valid to ALE Low	T <sub>OSC</sub> -15		ns
T <sub>LLAX</sub>	Address Hold after ALE/ADV# Low	T <sub>OSC</sub> -40		ns
T <sub>LLRL</sub>	ALE/ADV# Low to RD# Low	T <sub>OSC</sub> -30		ns

NOTES:

1. Testing performed at 4 MHz, however, the device is static by design and typically operates below 1 Hz.

2. Typical specifications, not guaranteed.

3. Assuming back-to-back bus cycles.

4. 8-bit bus only.

5. If wait states are used, add 2T<sub>OSC</sub> x n = number of wait states. If mode 0 (1 automatic wait state added)

operation is selected, add  $2T_{OSC}$  to specification. 6.  $T_{OFD}$  is the time for the oscillator fail detect circuit (OFD) to react to a clock failure. The OFD circuitry is enabled by programming the UPROM location 0778H with the value 0004H. Programming the CDE bit enables oscillator fail detection.

Symbol	Parameter	Min	Мах	Units
T <sub>RLCL</sub>	RD Low to CLKOUT Low CA CB	+ 4 -8	+ 30 + 20	ns
T <sub>RLRH</sub>	RD# Low Period	T <sub>OSC</sub> -10		ns (5)
T <sub>RHLH</sub>	RD# High to ALE/ADV# High	T <sub>OSC</sub>	T <sub>OSC</sub> +25	ns (3)
T <sub>RLAZ</sub>	RD# Low to Address Float		5	ns
T <sub>LLWL</sub>	ALE/ADV# Low to WR# Low	T <sub>OSC</sub> -10		ns
T <sub>CLWL</sub>	CLKOUT Low to WR# Low	-5	+ 25	ns
T <sub>QVWH</sub>	Data Valid before WR# High	T <sub>OSC</sub> -23		ns
Т <sub>СНWН</sub>	CLKOUT High to WR# High	-10	+ 15	ns
T <sub>WLWH</sub>	WR# Low Period CA CB	T <sub>OSC</sub> -30 T <sub>OSC</sub> -20		ns (5)
T <sub>WHQX</sub>	Data Hold after WR# High	T <sub>OSC</sub> -25		ns
T <sub>WHLH</sub>	WR# High to ALE/ADV# High	T <sub>OSC</sub> -10	T <sub>OSC</sub> +15	ns (3)
T <sub>WHBX</sub>	BHE#, INST Hold after WR# High	T <sub>OSC</sub> -10		ns
T <sub>WHAX</sub>	AD8-15 Hold after WR# High	T <sub>OSC</sub> -30		ns (4)
T <sub>RHBX</sub>	BHE#, INST Hold after RD# High	T <sub>OSC</sub> -10		ns
T <sub>RHAX</sub>	AD8-15 Hold after RD# High	T <sub>OSC</sub> -30		ns (4)

### Table 6. AC Characteristics the 87C196CA/87C196CB - Express Meets (Sheet 2 of 2)

#### NOTES:

Testing performed at 4 MHz, however, the device is static by design and typically operates below 1 Hz.
 Typical specifications, not guaranteed.

Assuming back-to-back bus cycles.
 8-bit bus only.

a. 8-bit bus only.
 If wait states are used, add 2T<sub>OSC</sub> x n = number of wait states. If mode 0 (1 automatic wait state added) operation is selected, add 2T<sub>OSC</sub> to specification.
 T<sub>OFD</sub> is the time for the oscillator fail detect circuit (OFD) to react to a clock failure. The OFD circuitry is enabled by programming the UPROM location 0778H with the value 0004H. Programming the CDE bit enables oscillator fail detection.



Symbol	Parameter	Min	Мах	Units
T <sub>AVYV</sub>	Address Valid to Ready Setup		20	ns (3)
T <sub>LLYV</sub>	ALE Low to Ready Setup		250	ns (3)
T <sub>YLYH</sub>	Non Ready Time	No Up	per Limit	ns
T <sub>CLYX</sub>	READY Hold after CLKOUT Low	0	T <sub>OSC</sub> -30	ns (1)
T <sub>AVGV</sub>	Address Valid to BUSWIDTH Setup		T <sub>OSC</sub> -75	ns (2,3)
T <sub>LLGV</sub>	ALE Low to BUSWIDTH Setup		T <sub>OSC</sub> –60	ns (2,3)
T <sub>CLGX</sub>	BUSWIDTH Hold after CLKOUT Low	0		ns
T <sub>AVDV</sub>	Address Valid to Input Data Valid		3T <sub>OSC</sub> –55	ns (2)
T <sub>RLDV</sub>	RD# Active to Input Data Value CA CB		T <sub>OSC</sub> -22 T <sub>OSC</sub> -30	ns (2)
T <sub>CLDV</sub>	CLKOUT Low to Input Data Valid		3T <sub>OSC</sub> -50	ns
T <sub>RHDZ</sub>	End of RD# to INput Data Valid			ns
T <sub>RHDX</sub>	Data Hold after RD# High	0		ns

### Table 7. AC Characteristics System Must Meet to Work with 87C196CA/87C196CB - Express

NOTES:

1. Testing performed at 4 MHz, however, the device is static by design and typically operates below 1 Hz.

2. Typical specifications, not guaranteed.

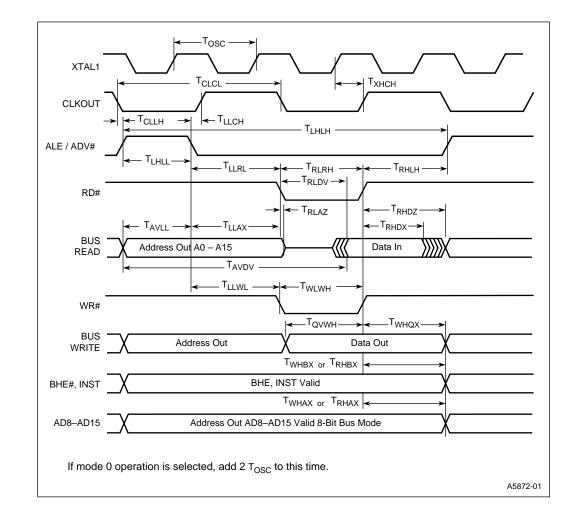
3. Assuming back-to-back bus cycles.

4. 8-bit bus only.

If wait states are used, add 2T<sub>OSC</sub> x n = number of wait states. If mode 0 (1 automatic wait state added) operation is selected, add 2T<sub>OSC</sub> to specification.
 T<sub>OFD</sub> is the time for the oscillator fail detect circuit (OFD) to react to a clock failure. The OFD circuitry is

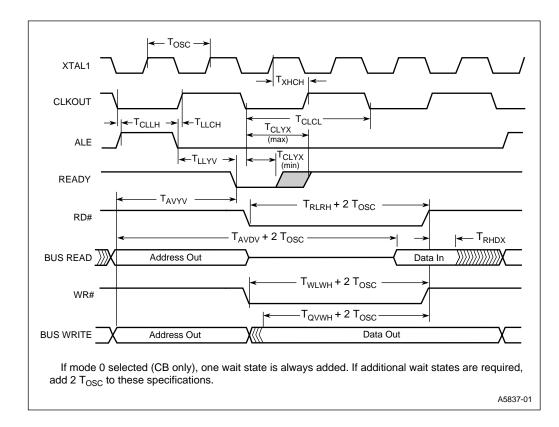
6. T<sub>OFD</sub> is the time for the oscillator fail detect circuit (OFD) to react to a clock failure. The OFD circuitry is enabled by programming the UPROM location 0778H with the value 0004H. Programming the CDE bit enables oscillator fail detection.

### 5.2.2 87C196CA/87C196CB - Express Timings



### Figure 8. 87C196CA/87C196CB - Express System Bus Timing

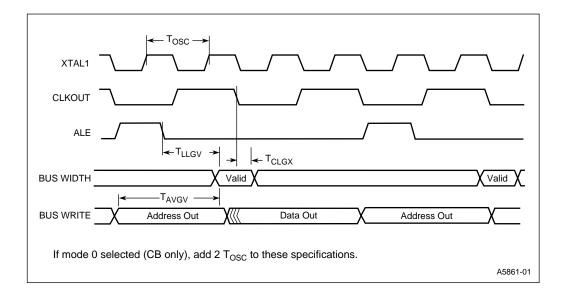




### Figure 9. 87C196CA/87C196CB - Express Ready Timings (One Wait State)

### 5.2.3 87C196CB Timings





### 5.2.4 8xC196CB Timings

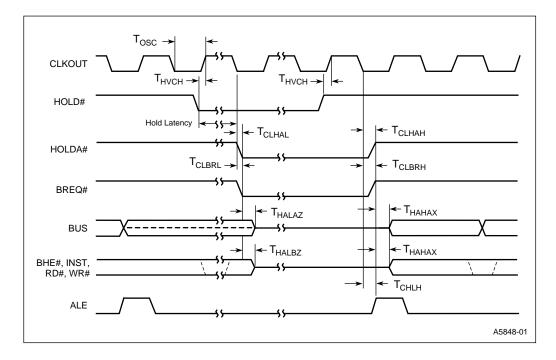
### Table 8. 8xC196CB HOLD#/HOLDA# Timings (Over Specified Operation Conditions)

Symbol	Parameter	Min	Max	Units
T <sub>HVCH</sub>	HOLD Setup Time	+ 65		ns (1)
T <sub>CLHAL</sub>	CLKOUT Low to HLDA Low	-15	+ 15	ns
T <sub>CLBRL</sub>	CLKOUT Low to BREQ Low	-15	+ 15	ns
T <sub>AZHAL</sub>	HLDA Low to Address Float		+ 25	ns
T <sub>BZHAL</sub>	HLDA Low to BHE#, INST, RD#, WR# Weakly Driven		+ 25	ns
T <sub>CLHAH</sub>	CLKOUT Low to HLDA High	-15	+ 15	ns
T <sub>CLBRH</sub>	CLKOUT Low to BREQ High	-25	+ 25	ns
T <sub>HAHAX</sub>	HLDA High to Address No Longer Float	-15		ns
T <sub>HAHBV</sub>	HLDA High to BHE#, INST, RD#, WR# Valid	-10	+ 15	ns

NOTE:

1. To guarantee recognition at next clock.

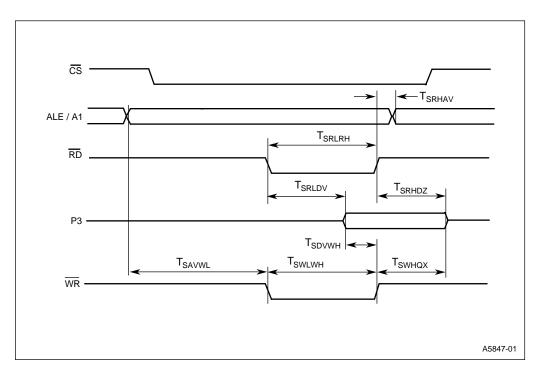
### Figure 11. 87C196CB HOLD#/HOLDA# Timings



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#### **8xC196CB AC Characteristics - Slave Port** 5.2.5

### Figure 12. Slave Port Waveform - (SLPL = 0)



### Table 9. Slave Port Timing - (SLPL = 0, 1, 2, 3)

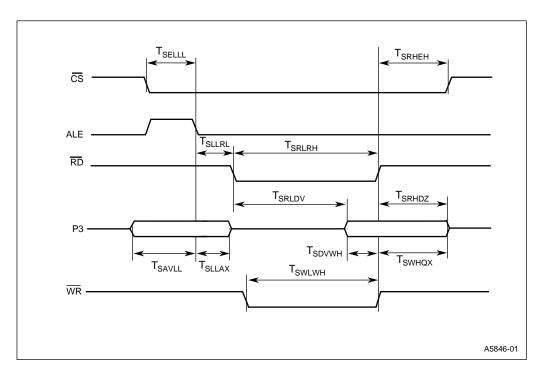
Symbol	Parameter	Min	Max	Units
T <sub>SAVWL</sub>	Address Valid to WR# Low	50		ns
T <sub>SRHAV</sub>	RD# High to Address Valid	60		ns
T <sub>SRLRH</sub>	RD# Low Period	T <sub>OSC</sub>		ns
T <sub>SWLWH</sub>	WR# Low Period	T <sub>OSC</sub>		ns
T <sub>SRLDV</sub>	RD# Low to Output Data Valid		60	ns
T <sub>SDVWH</sub>	Input Data Setup to WR# High	20		ns
T <sub>SWHQX</sub>	WR# High to Data Invalid	30		ns
T <sub>SRHDZ</sub>	RD# High to Data Float	15		ns

NOTE:

1. Test Conditions:

- $F_{OSC} = 16 \text{ MHz}$   $T_{OSC} = 60 \text{ ns}$  Rise/Fall Time = 10 ns
- Capacitive Pin Load = 100 pF
- 2. These values are not tested in production, and are based upon theoretical estimates and/or laboratory tests.
- 3. Specifications above are advance information and are subject to change.





### Table 10. Slave Port Timing - (SLPL = 1, 2, 3)

Symbol	Parameter	Min	Max	Units
T <sub>SELLL</sub>	CS# Low to ALE Low	20		ns
T <sub>SRHEH</sub>	RD# or WR# High to CS# High	60		ns
T <sub>SLLRL</sub>	ALE Low to RD# Low	T <sub>OSC</sub>		ns
T <sub>SRLRH</sub>	RD# Low Period	T <sub>OSC</sub>		ns
T <sub>SWLWH</sub>	WR# Low Period	T <sub>OSC</sub>		ns
T <sub>SAVLL</sub>	Address Valid to ALE Low	20		ns
T <sub>SLLAX</sub>	ALE Low to Address Invalid	20		ns
T <sub>SRLDV</sub>	RD# Low to Output Data Valid		60	ns
T <sub>SDVWH</sub>	Input Data Setup to WR# High	20		ns
T <sub>SWHQX</sub>	WR# High to Data Invalid	30		ns
T <sub>SRHDZ</sub>	RD# High to Data Float	15		ns

NOTE:

1. Test Conditions:

•  $F_{OSC} = 16 \text{ MHz}$ •  $T_{OSC} = 60 \text{ ns}$ • Rise/Fall Time = 10 ns

Capacitive Pin Load = 100 pF

2. These values are not tested in production, and are based upon theoretical estimates and/or laboratory tests.

3. Specifications above are advance information and are subject to change.

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### Table 11. Normal Master/Slave Operation

Symbol	Parameter	Min (1)	Мах	Units
Т <sub>СНСН</sub>	Clock Period	4t		ns
T <sub>CLCH</sub>	Clock Low Time/Clock High Time	2t–10		ns (2)
T <sub>CLDV</sub>	Clock Falling to Data Out Valid (Master)	0.5t	1.5t + 20	ns
T <sub>CLDV1</sub>	Clock Falling to Data Out Valid (Slave)	0.5t	1.5t + 20	ns
T <sub>DVCH</sub>	Data In Setup to Clock Rising Edge	10		ns
T <sub>CHDX</sub>	Clock Rising Edge to Data In Invalid	t + 15		ns

NOTE:

t = 1 state time (125 ns @ 16 MHz).
 Timings are guaranteed by design.

### Table 12. Handshake Operation

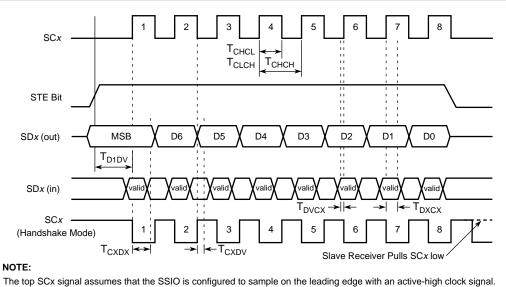
Symbol	Parameter	Min (1)	Мах	Units
Тснсн	Clock Period	4t		ns
T <sub>CLCH</sub>	Clock Low Time/Clock High Time	2t–10		ns (2)
T <sub>CLDV</sub>	Clock Falling to Data Out Valid (Master)	0.5t	1.5t + 20	ns
T <sub>CLDV1</sub>	Clock Falling to Data Out Valid (Slave)	0.5t	1.5t + 20	ns
T <sub>DVCH</sub>	Data In Setup to Clock Rising Edge	10		ns
T <sub>CHDX</sub>	Clock Rising Edge to Data In Invalid	t + 15		ns

NOTE:

1. t = 1 state time (125 ns @ 16 MHz).

This specification refers to input clocks during slave operation. During master operation, the device outputs a nominal 50% duty cycle clock.

### Figure 14. Synchronous Serial Port



The top SCx signal assumes that the SSIO is configured to sample on the leading edge with an active-high clock signal. The CSx signal will be different for other configurations, however, setup and hold timings will still be the same in relation to the latching edge of SCx.

A5845-01

### Table 13. External Clock Drive

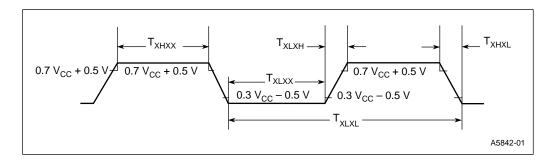
Symbol	Parameter	Min (1)	Max	Units
1/T <sub>XLXL</sub>	Oscillator Frequency	4	16	MHz
T <sub>XLXL</sub>	Oscillator Period (T <sub>OSC</sub> )	62.5	250	ns
T <sub>XHXX</sub>	High TIme	0.35 x T <sub>OSC</sub>	0.65 T <sub>OSC</sub>	ns
T <sub>XLXX</sub>	Low Time	0.35 x T <sub>OSC</sub>	0.65 T <sub>OSC</sub>	ns
T <sub>XLXH</sub>	Rise TIme		10	ns
T <sub>XHXL</sub>	Fall Time		10	ns

NOTE:

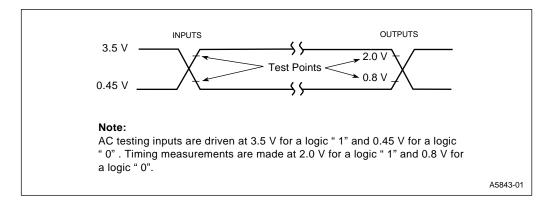
1. t = 1 state time (125 ns @ 16 MHz).

2. This specification refers to input clocks during slave operation. During master operation, the device outputs a nominal 50% duty cycle clock.

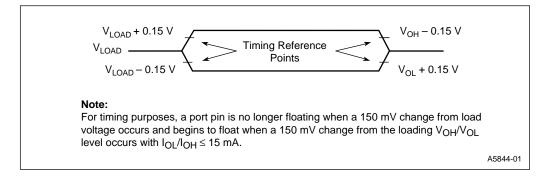
### Figure 15. External Clock Drive Waveforms



### Figure 16. Input Test Conditions



### **Figure 17. Output Test Conditions**



### 5.2.6 Explanation of AC Symbols

Each symbol is two pairs of letters prefixed by "T" for time. The characters in a pair indicate a signal and its condition, respectively. Symbols represent the time between the two signal/condition points.

### Table 14. Explanation of AC Symbols

Conditions	Signals	
H – High	A – Address	HA – HLDA#
L – Low	B – BHE#	L – ALE/ADV#
V – Valid	BR – BREQ#	Q – Data Out
X – No Longer Valid	C – CLKOUT	R – RD#
Z – Floating	D – DATA	W – WR#/WRH#/WRI#
	G – Buswidth	X – XTAL1
	H – HOLD#	Y – READY

#### 5.3 **EPROM Specifications**

#### **AC EPROM Programming Characteristics** 5.3.1

**Operating Conditions:** 

### Table 15. AC EPROM Programming Characteristics (Sheet 1 of 2)

Symbol	Parameter	Min	Max	Units
T <sub>AVLL</sub>	Address Setup Time	0		T <sub>osc</sub>
T <sub>LLAX</sub>	Address Hold Time	100		T <sub>OSC</sub>
T <sub>DVPL</sub>	Data Setup Time	0		T <sub>OSC</sub>
T <sub>PLDX</sub>	Data Hold Time	400		T <sub>OSC</sub>
T <sub>LLLH</sub>	PALE# Pulse Width	50		T <sub>OSC</sub>
T <sub>PLPH</sub>	PROG# Pulse Width (2) C/ Cl			T <sub>OSC</sub>
T <sub>LHPL</sub>	PALE# High to PROG# Low	220		T <sub>OSC</sub>
T <sub>PHLL</sub>	PROG# High to Next PALE# Low	220		T <sub>OSC</sub>
T <sub>PHDX</sub>	Word Dump Hold Time		50	T <sub>OSC</sub>
T <sub>PHPL</sub>	PROG# High to Next PROG# Low	220		T <sub>OSC</sub>
T <sub>LHPL</sub>	PALE# High to PROG# Low	220		T <sub>OSC</sub>
T <sub>PLDV</sub>	PROG# Low to Word Dump Valid C/ Cl		50 100	T <sub>OSC</sub>
T <sub>SHLL</sub>	RESET# High to First PALE# Low	1100		T <sub>OSC</sub>
T <sub>PHIL</sub>	PROG# High to AINC# Low	0		T <sub>OSC</sub>
T <sub>ILIH</sub>	AINC# Pulse Width	240		T <sub>OSC</sub>
T <sub>ILVH</sub>	PVER Hold after AINC# Low	50		T <sub>OSC</sub>
T <sub>ILPL</sub>	AINC# Low to PROG# Low	170		T <sub>OSC</sub>



#### Table 15. AC EPROM Programming Characteristics (Sheet 2 of 2)

Symbol	Parameter	Min	Max	Units
T <sub>PHVL</sub>	PROG# High to PVER# Valid		220	T <sub>OSC</sub>

NOTES:

1. Run time programming is done with  $F_{OSC} = 6 \text{ MHz}$  to 10 MHz,  $V_{CC}$ ,  $V_{PD}$ ,  $V_{REF} = 5 \text{ V} \pm 0.5 \text{ V}$ ,  $T_{C} = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$  and  $V_{PP} = 12.5 \text{ V} \pm 0.25 \text{ V}$ . For run-time programming over a full operating range, contact factory.

2. Programming Specifications are not tested, but guaranteed by design.

3. This specification is for the word dump mode. For programming pulses use 300  $T_{OSC}$  + 100 µs.

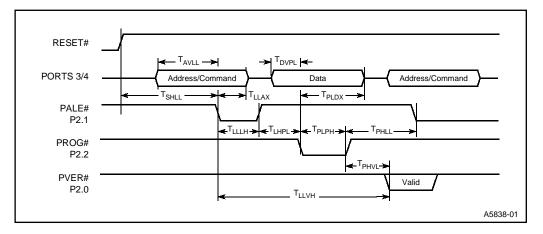
### **Table 16. DC EPROM Programming Characteristics**

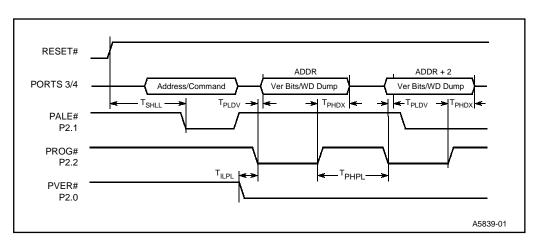
Symbol	Parameter	Min	Max	Units
I <sub>PP</sub>	V <sub>PP</sub> Programming Supply Current		200	mA

**NOTE:**  $V_{PP}$  must be within 1 V of  $V_{CC}$  while  $V_{CC} < 4.5$  V.  $V_{PP}$  must not have a low impedance path to ground or  $V_{SS}$  while  $V_{CC} > 4.5$  V.

#### 5.3.2 **EPROM Programming Waveforms**

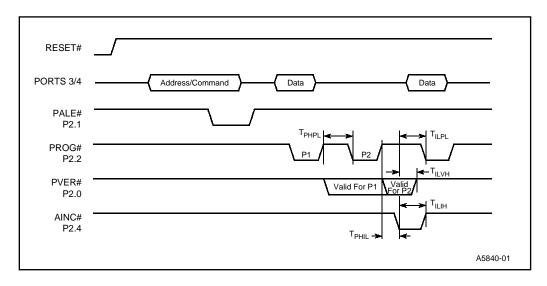
### Figure 18. Slave Programming Mode Data Program Mode with Single Program Pulse





### Figure 19. Slave Programming Mode in Word Dump or Data Verify Mode with Auto Increment







### 5.4 AC CHARACTERISTICS - Serial Port - Shift Register Mode

**Operating Conditions:** 

- $T_A = -40^{\circ}C + 85^{\circ}C$
- $V_{SS} = 0.0 V$
- $V_{CC} = 5.0 \text{ V} \pm 10\%$
- Load Capacitance = 100 pF

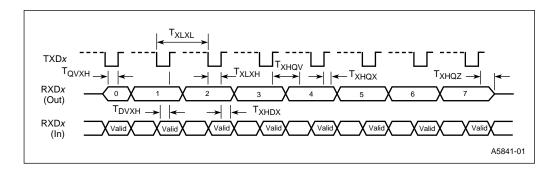
### Table 17. Serial Port Timing - Shift Register Mode

Symbol	Parameter	Min	Мах	Units
T <sub>XLXL</sub>	Serial Port Clock Period	8 T <sub>OSC</sub>		ns
T <sub>XLXH</sub>	Serial Port Clock Falling Edge to Rising Edge	4 T <sub>OSC</sub> – 50	4 T <sub>OSC</sub> + 50	ns
T <sub>QVXH</sub>	Output Data Setup to Clock Rising Edge	3 T <sub>OSC</sub>		ns
T <sub>XHQX</sub>	Output Data Hold after Clock Rising Edge	2 T <sub>OSC</sub> – 50		ns
T <sub>XHQV</sub>	Next Output Data Valid after Clock Rising Edge		2 T <sub>OSC</sub> + 50	ns
T <sub>DVXH</sub>	Input Data Setup to Clock Rising Edge	2 T <sub>OSC</sub> – 200		ns
T <sub>XHDX</sub> (1)	Input Data Hold after Clock Rising Edge	0		ns
T <sub>XHQZ</sub> (1)	Last Clock Rising to Output Float		5T <sub>OSC</sub>	ns

NOTE:

1. Parameter not tested.

### Figure 21. Waveform - Serial Port - Shift Register Mode 0

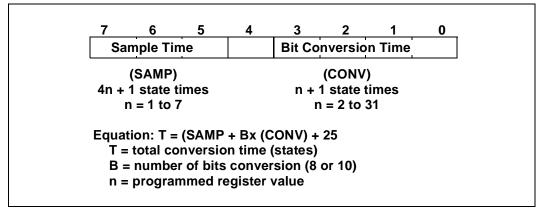


### 5.4.1 A/D Characteristics

The sample and conversion time of the A/D converter in the 8-bit or 10-bit modes is programmed by loading a byte into the AD\_TIME Special Function Register. This allows optimizing the A/D operation for specific applications. The AD\_TIME register is functional for all possible values, but the accuracy of the A/D converter is only guaranteed for the times specified in the operating conditions table.

The value loaded into AD\_TIME bits 5, 6, 7 determines the sample time, SAMP. The value loaded into AD\_TIME bits 0, 1, 2, 3 and 4 determines the bit conversion time, CONV. These bits, as well as the equation for calculating the total conversion time, T, are shown in Figure 22.

### Figure 22. AD\_TIME 1FAFH:Byte



The converter is ratiometric, so absolute accuracy is dependent on the accuracy and stability of  $V_{REF}$ .  $V_{REF}$  must be closed to  $V_{CC}$  since it supplies both the resistor ladder and the analog portion of the converter and input port pins. There is also an AD\_TEST SFR that allows for conversion on ANGND and  $V_{REF}$  as well as adjusting the zero offset. The absolute error listed is without doing any adjustments.

### 5.4.1.1 A/D Converter Specification

The specifications given assume adherence to the operating conditions section of this data sheet. Testing is performed with  $V_{REF} = 5.12$  V and 16 MHz operating frequency. After a conversion is started, the device is placed in IDLE mode until the conversion is completed.

### Table 18. 10-Bit Mode A/D Operating Conditions

Symbol	Parameter	Min	Мах	Units
T <sub>A</sub>	Ambient Temperature	-40	+85	°C
V <sub>CC</sub>	Digital Supply Voltage	4.5	5.5	V
V <sub>REF</sub>	Analog Supply Voltage	4.5	5.5 (1)	V
T <sub>SAM</sub>	Sample Time	2		µs (2)
T <sub>CONV</sub>	Conversion Time	15	18	µs (2)
F <sub>OSC</sub>	Oscillator Frequency	4	16	MHz

NOTES:

1.  $V_{\text{REF}}$  must be within+0.5 V of  $V_{\text{CC}}.$ 

2. The value of AD\_TIME is selected to meet these specifications.

Parameter	Typical (2,3)	Min	Max	Units (4)	Notes
Resolution		1024 10	1024 10	Levels Bits	
Absolute Error		0	± 3	LSBs	
Full-scale Error	$0.25\pm0.5$			LSBs	
Zero Offset Error	$0.25\pm0.5$			LSBs	
Non-Linearity	1 ± 2		± 3	LSBs	
Differential Non-Linearity		> - 0.75	+ 0.75	LSBs	
Channel-to-Channel Matching	± 0.1	0	± 1	LSBs	
Repeatability	± 0.25	0		LSBs	(2)
Temperature Coefficients: Offset Fullscale Differential Non-Linearity	0.009			LSB/C	(2)
Off Isolation		- 60		dB	(2,4,5)
Feedthrough	- 60			dB	(2,4)
V <sub>CC</sub> Power Supply Rejection	- 60			dB	(2,4)
Input Resistance		750	1.2 K	Ω	(2)
DC Input Leakage	± 1	0	± 3	μA	
Voltage on Analog Input Pin		ANGND -0.5	V <sub>REF</sub> + 0.5	V	(7)
Sampling Capacitor	3			pF	

### Table 19. 10-Bit Mode A/D Characteristics (Using Above Operating Conditions) (1)

#### NOTES:

1. All conversions performed with processor in IDLE mode.

2. These values are expected for most parts at 25°C but are not tested or guaranteed.

These values are not tested in production and are based on theoretical estimates and/or laboratory test.
 An "LSB", as used here, has a value of approximately 5 mV

5. DC to 100 KHz

6. Multiplexer Break-Before-Make Guaranteed.

7. Applying voltages beyond these specifications will degrade the accuracy of other channels being converted.

### Table 20. 8-Bit Mode A/D Operating Conditions

Symbol	Parameter	Min	Мах	Units
T <sub>A</sub>	Ambient Temperature	-40	+85	°C
V <sub>CC</sub>	Digital Supply Voltage	4.5	5.5	V
V <sub>REF</sub>	Analog Supply Voltage	4.5	5.5 (1)	V
T <sub>SAM</sub>	Sample Time	2		µs (2)
T <sub>CONV</sub>	Conversion Time	12	15	µs (2)
F <sub>OSC</sub>	Oscillator Frequency	4	16	MHz

#### NOTES:

1.  $V_{REF}$  must be within+0.5 V of  $V_{CC}$ . 2. The value of AD\_TIME is selected to meet these specifications.

Parameter	Typical (2,3)	Min	Мах	Units (4)	Notes
Resolution		256 8	1024 10	Levels Bits	
Absolute Error		0	± 1	LSBs	
Full-scale Error	± 0.5			LSBs	
Zero Offset Error	± 0.5			LSBs	
Non-Linearity			± 1	LSBs	
Differential Non-Linearity		> - 0.75	+ 0.5	LSBs	
Channel-to-Channel Matching		0	± 1	LSBs	
Repeatability	± 0.25	0		LSBs	(2)
Temperature Coefficients: Offset Fullscale Differential Non-Linearity	0.003			LSB/C	(2)
Off Isolation		- 60		dB	(2,4,5)
Feedthrough	- 60			dB	(2,4)
V <sub>CC</sub> Power Supply Rejection	- 60			dB	(2,4)
Input Resistance		750	1.2 K	Ω	(2)
DC Input Leakage	± 1	0	± 1.5	μA	
Voltage on Analog Input Pin		ANGND -0.5	V <sub>REF</sub> + 0.5	V	(7)
Sampling Capacitor	3			pF	

### Table 21. 8-Bit Mode A/D Characteristics (Using Above Operating Conditions) (1)

#### NOTES:

1. All conversions performed with processor in IDLE mode.

2. These values are expected for most parts at 25°C but are not tested or guaranteed.

These values are not tested in production and are based on theoretical estimates and/or laboratory test.
 An "LSB", as used here, has a value of approximately 5 mV

5. DC to 100 KHz

6. Multiplexer Break-Before-Make Guaranteed.

7. Applying voltages beyond these specifications will degrade the accuracy of other channels being converted.



### 5.4.2 87C196CA Design Considerations

The 87C196CA device is a memory scalar of the 87C196KR device with integrated CAN 2.0. The CA is designed for strict functional and electrical compatibility to the Kx family as well as integration of on-chip networking capability. The 87C196CA has fewer peripheral functions than the 196KR, due in part to the integration of the CAN peripheral. Following are the functionality differences between the 196KR and 196CA devices.

196KR Features Unsupported on the 196CA:

- Analog Channels 0 and 1
   External Clocking/Direction of Timer1
- INST Pin Functionality
   Quadrature Clocking Timer 1
- SLPINT and SLPCS Pin Support
   Dynamic Buswidth
- HLD/HLDA Functionality
- EPA Capture Channels 4±7
- 1. **External Memory**. Removal of the Buswidth pin means the bus cannot dynamically switch from 8- to 16-bit bus mode or vice versa. The programmer must define the bus mode by setting the associated bits in the CCB.
- 2. Auto-Programming Mode. The 87C196CA device will ONLY support the 16-bit zero wait state bus during auto-programming.
- 3. **EPA4 through EPA7**. Since the CA device is based on the KR design, these functions are in the device, however there are no associated pins. A programmer can use these as compare only channels or for other functions like software timer, start an A/D conversion, or reset timers.
- 4. **Slave Port Support**. The Slave port can not be used on the 196CA due to a function change for P5.4/SLPINT and P5.1/SLPCS not being bonded-out.
- 5. **Port Functions**. Some port pins have been removed. P5.1, P6.2, P6.3, P1.4 through P1.7, P2.3, P2.5, P0.0 and P0.1. The PxREG, PxSSEL, and PxIO registers can still be updated and read. The programmer should not use the corresponding bits associated with the removed port pins to conditionally branch in software. Treat these bits as RESERVED.

Additionally, these port pins should be setup internally by software as follows:

- Written to PxREG as ``1" or ``0".
- Configured as Push/Pull, PxIO as ``0".
- Configured as LSIO.

This configuration will effectively strap the pin either high or low. DO NOT Configure as Open Drain output `'1", or as an Input pin. This device is CMOS.

- 6. **EPA Timer RESET/Write Conflict**. If the user writes to the EPA timer at the same time that the timer is reset, it is indeterminate which will take precedence. Users should not write to a timer if using EPA signals to reset it.
- 7. Valid Time Matches. The timer must increase/decrease to the compare value for a match to occur. A match does not occur if the timer is loaded with a value equal to an EPA compare value. Matches also do not occur if a timer is reset and 0 is the EPA compare value.
- 8. Write Cycle during Reset. If RESET occurs during a write cycle, the contents of the external memory device may be corrupted.
- 9. **Indirect Shift Instruction**. The upper 3 bits of the byte register holding the shift count are not masked completely. If the shift count register has the value 32 c n, where n e 1, 3, 5, or 7, the operand will be shifted 32 times. This should have resulted in no shift taking place.
- 10. P2.7 (CLKOUT). P2.7 (CLKOUT) does not operate in open drain mode.



### 5.4.3 87C196CA ERRATA

This data sheet was published prior to first available silicon. Consequently, there is no known errata at this time.

### 5.4.4 87C196CA DESIGN CONSIDERATIONS

### 1. **PORT0**

On the 87C196CA the analog inputs for P0.0 and P0.1 have been multiplexed and tied to  $V_{REF}$ . Therefore, initiating an analog conversion on ACH0 or ACH1 results in a value equal to full scale (3FFh). On the CA, the digital inputs for these two channels are tied to ground, therefore, reading P0.0 or P0.1 results in a digital "0".

### **2. PORT1**

On the 87C196CA, P1.4, P1.5, P1.6 and P1.7 have been removed from the device and is not available to the programmer. Corresponding bits in the port registers have been "hard-wired" to provide the following results when read:

Regis	When Read	
P1_PIN.x	(x = 4,5,6,7)	1
P1_REG.x	(x = 4,5,6,7)	1
P1_DIR.x	(x = 4,5,6,7)	1
P1_MODE.x	(x = 4,5,6,7)	0

**NOTE:** Writing to these bits has no effect.

### **3. PORT2**

On the 87C196CA, P2.3 and P2.5 have been removed from the device and are not available to the programmer. Corresponding bits in the port registers have been "hard-wired" to provide the following results when read.

Regist	When Read	
P2_PIN.x	(x = 3,5)	1
P2_REG.x	(x = 3,5)	1
P2_DIR.x	(x = 3,5)	1
P2_MODE.x	(x = 3,5)	0

**NOTE:** Writing to these bits has no effect.

### **4. PORT5**

On the 87C196CA, P5.1 and P5.7 have been removed from the device and are not available to the programmer. Corresponding bits in the port registers have been "hard-wired" to provide the following results when read:

Reg	When Read	
P5_PIN.x	(x = 1,7)	1
P5_REG.x	(x = 1,7)	1
P5_DIR.x	(x = 1,7)	1
P5_MODE.x	(x = 1)	0
P5_MODE.x	(x = 7)	1

**NOTE:** Writing to these bits has no effect.



### **5. PORT6**

On the 87C196CA, P6.2 and P6.3 have been removed from the device and are not available to the programmer. Corresponding bits in the port registers have been "hard-wired" to provide the following results when read:

Register Bits		When Read
P6_PIN.x	(x = 2,3)	1
P6_REG.x	(x = 2,3)	1
P6_DIR.x	(x = 2,3)	1
P6_MODE.x	(x = 2,3)	0

**NOTE:** Writing to these bits has no effect.

### 6.0 DATASHEET REVISION HISTORY

This is the -001 version of the "87C196CA/87C196CB - Express" datasheet.